

RSD046P05

Pch 45V 4.5A Power MOSFET

V_{DSS}	-45V
R _{DS(on)} (Max.)	155m Ω
I _D	−4.5A
P_D	15W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

Application

Switching Power Supply

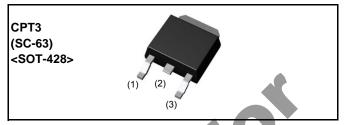
Automotive Motor Drive

Automotive Solenoid Drive

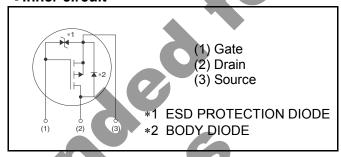
•Absolute maximum ratings($T_a = 25^{\circ}C$)

Paramete		Symbol	Value	Unit
Drain - Source voltage		V _{DSS}	-45	V
Continuous drain current	T _c = 25°C	I _D *1	±4.5	А
Continuous diam current	T _c = 100°C	I _D *1	±2.4	А
Pulsed drain current		I _{D,pulse} *2	±9.0	А
Gate - Source voltage	V_{GSS}	±20	V	
Avalanche energy, single pulse	E _{AS} *3	14.3	mJ	
Avalanche current		I _{AR} *3	-4.5	А
Power dissipation	T _c = 25°C	P _D	15	W
T _a = 25° C		P _D	0.85	W
Junction temperature	T _j	150	°C	
Range of storage temperature		T _{stg}	-55 to +150	°C

Outline



●Inner circuit



Packaging specifications

OT GONG	ging specifications	
	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
(2	Taping code	TL
	Marking	046P05

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Зуппоп	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	8.33	°C/W

•Electrical characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions		Values		
Parameter	Syllibol			Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = -1mA$	- 4 5	**	-	V
		$V_{DS} = -45V, V_{GS} = 0V$			-1	
Zoro gato voltago drain current	lass	T _j = 25°C		_	-1	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -45V, V_{GS} = 0V$			-100	μА
		T _j = 125°C	_	Y	-100	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	4	-	±10	μΑ
Gate threshold voltage	V _{GS (th)}	$V_{DS} = -10V, I_{D} = -1mA$	-1	-	-3	V
		$V_{GS} = -10V$, $I_D = -4.5A$	-	110	155	
		$V_{GS} = -4.5V$, $I_D = -4.5A$	-	160	225	
Static drain - source on - state resistance	R _{DS(on)} *4	$V_{GS} = -4.0V$, $I_D = -4.5A$	-	185	260	$m\Omega$
		$V_{GS} = -10V, I_D = -4.5A$		100	250	
		T _i = 125°C	_	180	250	
Forward transfer admittance	g _{fs}	$V_{DS} = -10V, I_D = -4.5A$	3	6	-	S



●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii e lei	Syllibol	Symbol Conditions		Min. Typ. Max.		
Input capacitance	C _{iss}	V _{GS} = 0V	-	550	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	100	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	50		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -25V$, $V_{GS} = -10V$	-	8		
Rise time	t _r *4	$I_D = -2.0A$	-	8	-	no
Turn - off delay time	t _{d(off)} *4	$R_L = 12\Omega$	- (35	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-7/	8	-	

●Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ailletei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg *4	V _{DD} ≃ -25V		12	-	
Gate - Source charge	Q _{gs} *4	$I_D = -4.5A$		2.2	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = -5V	-	2.2	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq -30V$, $I_D = -4.5A$	-	-3.4	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Cymbol	cymbol Conditions		Values		
Parameter	Syllibol	Conditions	Min.	Тур.	Max.	Unit
Continuous source current	l _s *1	T _c = 25°C	-	6	-4.5	Α
Pulsed source current	I _{SM} *2	1 c = 25 G	-	-	-9	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = -4.5A$	-	-	-1.2	V
Reverse recovery time	t _{rr} *4	I _S = -4.5A	-	40	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = -100A/μs	-	60	-	μС

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L \simeq 1mH, V_{DD} = -25V, Rg = 10Ω , starting T_j = $25^{\circ}C$

^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve

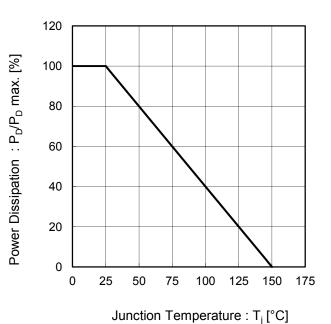
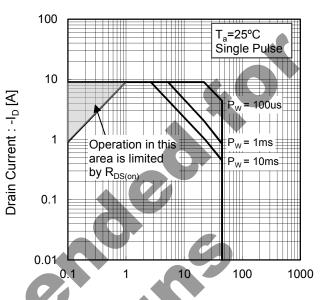
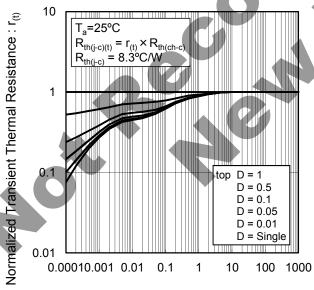


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw [s]

Fig.4 Avalanche Current vs Inductive Load

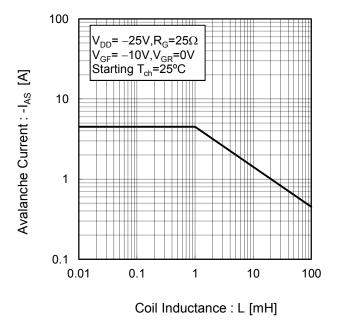
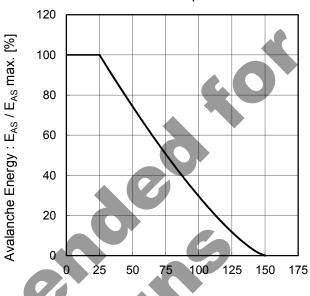
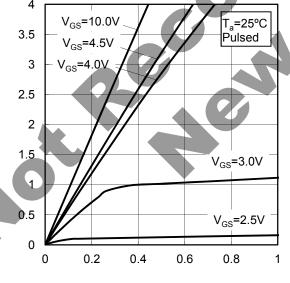


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



Junction Temperature : T_i [°C]

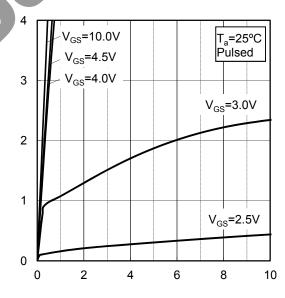
Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : -V_{DS} [V]

Drain Current : -l_D [A]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : -V_{DS} [V]

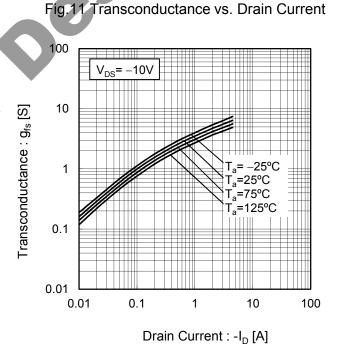
Drain Current: -I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 60 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 55 $I_D = -1mA$ 50 45 $: -V_{(BR)DSS}[V]$ 40 35 30 25 20 -50 0 50 100 150 Junction Temperature : T_i [°C]

Gate - Source Voltage : -V_{GS} [V]

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature 3.0 V_{DS} = -10V Gate Threshold Voltage: -VGS(th) [V] $I_D = -1mA$ 2.5 2.0 1.5 1.0 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T_i [°C]





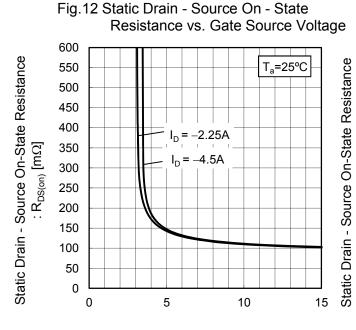
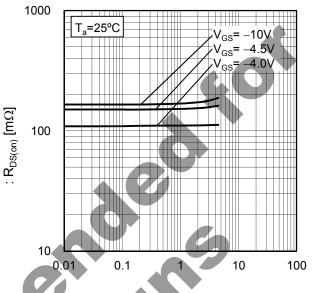


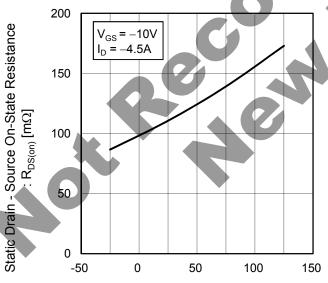
Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)



Gate - Source Voltage : -V_{GS} [V]

Drain Current : -I_D [A]

Fig.14 Static Drain - Source On - State
Resistance vs. Junction Temperature



Junction Temperature : T_i [°C]

Resistance vs. Drain Current(II)

1000 $V_{GS} = -10V$ $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$

Drain Current : -I_D [A]

Fig.15 Static Drain - Source On - State

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

1000

V_{GS}= -4.5V

T_a=125°C

T_a=25°C

T_a=25°C

T_a=25°C

T_a=25°C

T_a=100

100

0.01

0.1

10

100

Drain Current : -I_D [A]

Fig. 17 Static Drain - Source On - State
Resistance vs. Drain Current(IV)

Ta=125°C
Ta=75°C
Ta=25°C
Ta=25°C
Ta=-25°C
Ta=

120 100 **Drain Current Dissipation** 80 : I_D/I_D max. (%) 60 40 20 0 25 50 0 75 100 125 150 175

Fig.18 Drain Current Derating Curve



Junction Temperature : T_i [°C]

Fig.19 Typical Capacitance

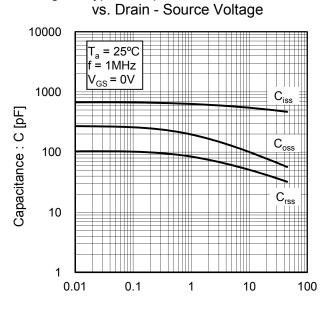
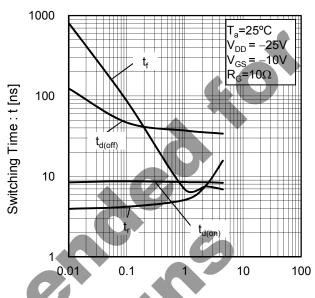


Fig.20 Switching Characteristics



Drain - Source Voltage : -V_{DS} [V]

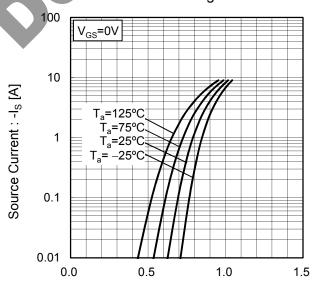
Drain Current : -I_D [A]

Fig.21 Dynamic Input Characteristics

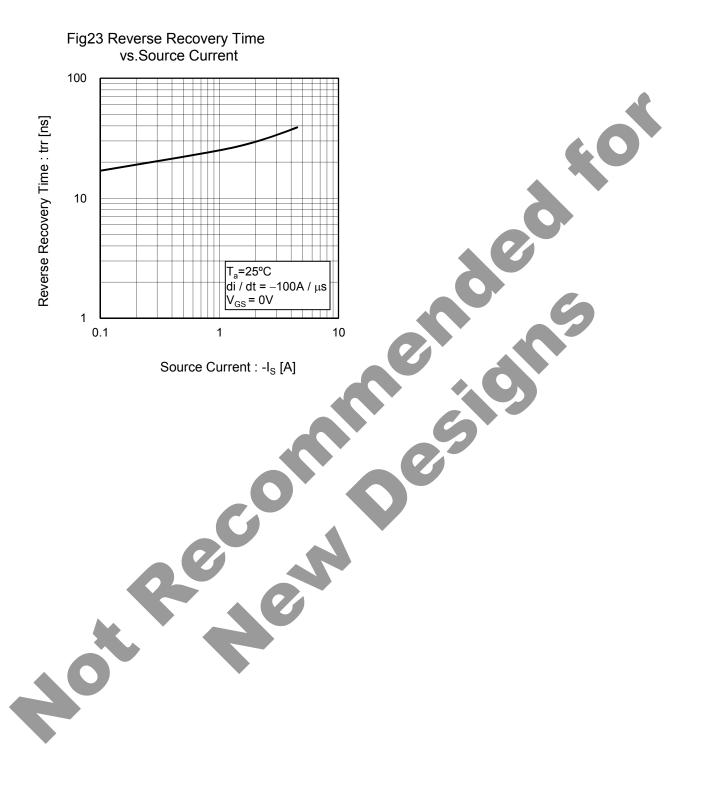
Ta=25°C $V_{DD}=-25V$ $V_{DD}=-4.5A$ $V_{D}=-4.5A$ V_{D}

Total Gate Charge : Q_g [nC]

Fig.22 Source Current vs. Source - Drain Voltage



Source-Drain Voltage : -V_{SD} [V]



●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

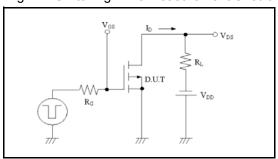


Fig.2-1 Gate Charge Measurement Circuit

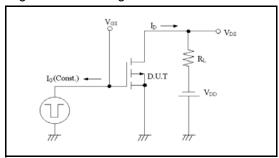


Fig.3-1 Avalanche Measurement Circuit

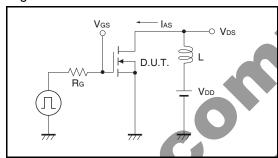


Fig.1-2 Switching Waveforms

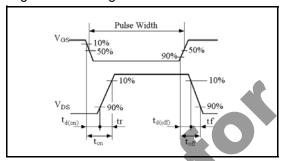


Fig.2-2 Gate Charge Waveform

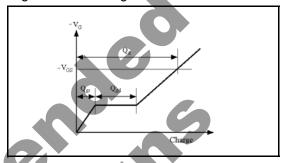
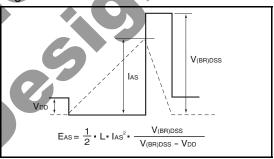
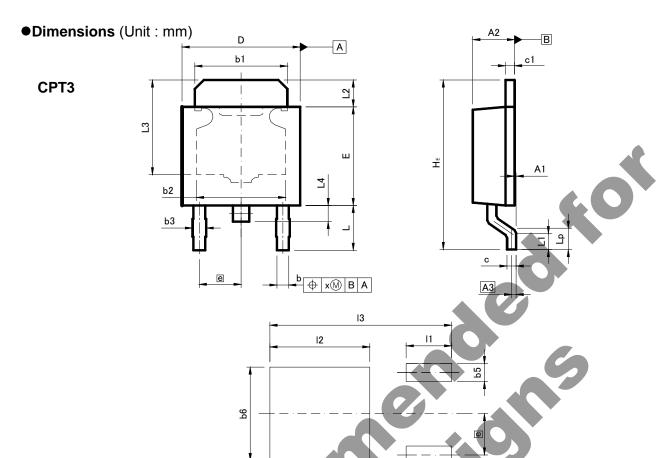


Fig.3-2 Avalanche Waveform





DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.15	0.000	0.006
A2	2.20	2.50	0.087	0.098
A3	0.2	25	0.0	10
b	0.55	0.75	0.022	0.030
b1	5.00	5.30	0.197	0.209
b2	5.0		0.1	97
b3	0.	75	0.0	30
C	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
E	5.40	5.80	0.213	0.228
е	2.3	30	0.0	91
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.110
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.30		0.209	
L4	0.9	90	0.0	
Lp	1.00	1.60	0.039	0.063
Х	-	0.25	_	0.010

Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
b5	_	1.00	_	0.04	
b6	-	5.20	-	0.205	
1	_	2.50	-	0.098	
12	_	5.50	-	0.217	
13	_	10.00	_	0.304	

Dimension in mm / inches

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JÁPAN	USA	EU	CHINA
	00/		OTHINA
CLASSⅢ	CLASSIII	CLASS II b	CLASSII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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